

FEATURES

- **1.8-V Phase Lock Loop Clock Driver for Double Data Rate (DDR II) Applications**
- **Spread Spectrum Clock Compatible**
- **Operating Frequency: 10 MHz to 400 MHz**
- **Low Current Consumption: <135 mA**
- **Low Jitter (Cycle-Cycle): ± 30 ps**
- **Low Output Skew: 35 ps**
- **Low Period Jitter: ± 20 ps**
- **Low Dynamic Phase Offset: ± 15 ps**

- **Low Static Phase Offset: ± 50 ps**
- **Distributes One Differential Clock Input to Ten Differential Outputs**
- **52-Ball μ BGA (MicroStar™ Junior BGA, 0.65-mm pitch) and 40-Pin MLF**
- **External Feedback Pins (FBIN, \overline{FBIN}) are Used to Synchronize the Outputs to the Input Clocks**
- **Meets or Exceeds JESD82-8 PLL Standard for PC2-3200/4300**
- **Fail-Safe Inputs**

DESCRIPTION

The CDCU877 is a high-performance, low-jitter, low-skew, zero-delay buffer that distributes a differential clock input pair (CK, \overline{CK}) to ten differential pairs of clock outputs (Y_n, $\overline{Y_n}$) and to one differential pair of feedback clock outputs (FBOUT, \overline{FBOUT}). The clock outputs are controlled by the input clocks (CK, \overline{CK}), the feedback clocks (FBIN, \overline{FBIN}), the LVCMS control pins (OE, OS), and the analog power input (AV_{DD}). When OE is low, the clock outputs, except FBOUT/ \overline{FBOUT} , are disabled while the internal PLL continues to maintain its locked-in frequency. OS (output select) is a program pin that must be tied to GND or V_{DD}. When OS is high, OE functions as previously described. When OS and OE are both low, OE has no affect on Y₇/ $\overline{Y_7}$, they are free running. When AV_{DD} is grounded, the PLL is turned off and bypassed for test purposes.

When both clock inputs (CK, \overline{CK}) are logic low, the device enters in a low power mode. An input logic detection circuit on the differential inputs, independent from input buffers, detects the logic low level and performs in a low power state where all outputs, the feedback, and the PLL are off. When the clock inputs transition from being logic low to being differential signals, the PLL turns back on, the inputs and the outputs are enabled, and the PLL obtains phase lock between the feedback clock pair (FBIN, \overline{FBIN}) and the clock input pair (CK, \overline{CK}) within the specified stabilization time.

The CDCU877 is able to track spread spectrum clocking (SSC) for reduced EMI. This device operates from -40°C to 85°C .

ORDERING INFORMATION

T _A	52-BALL BGA ⁽¹⁾	40-Pin MLF
-40°C to 85°C	CDCU877ZQL	CDCU877RHA
	CDCU877AZQL	CDCU877ARHA
	CDCU877GQL	CDCU877RTB
	CDCU877AGQL	CDCU877ARTB

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



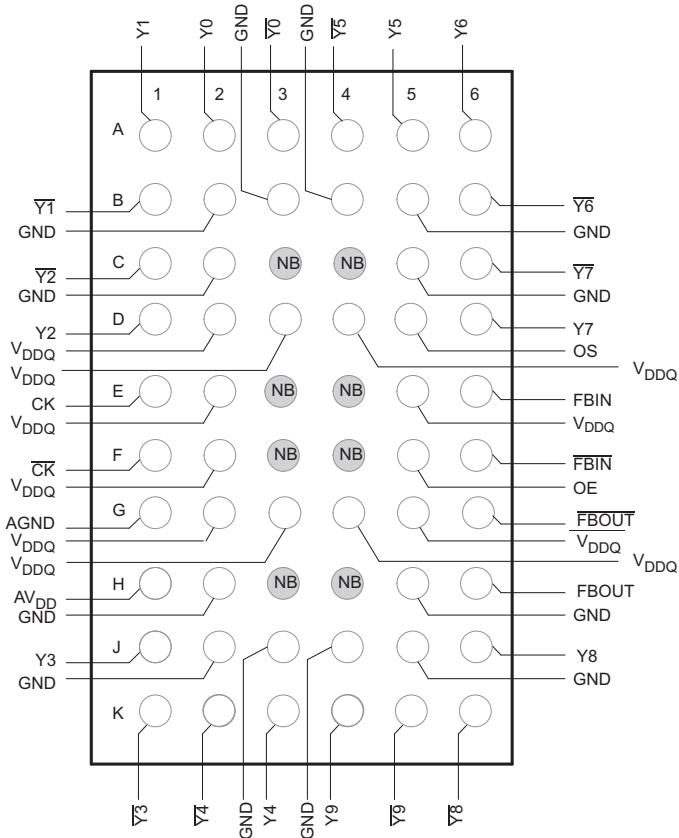
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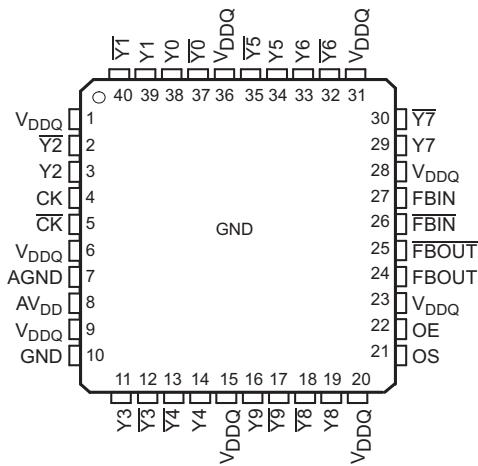
These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

MicroStar Junior (ZQL) Package (TOP VIEW)



- A. NC = No Connection
- B. NB = No Ball

RHA/RTB Package (MLF Package (TOP VIEW))



40-pin HP-VFQFP-N (6,0 x 6,0 mm Body Size, 0,5 mm Pitch, M0#220, Variation VJJD-2, E2 = D2 = 2,9 mm \pm 0,15 mm) Package Pinouts

TERMINAL FUNCTIONS

TERMINAL		RHA/RTB	I/O	DESCRIPTION
NAME	GQL/ZQL			
AGND	G1	7		Analog ground
AV _{DD}	H1	8		Analog power
CK	E1	4	I	Clock input with a (10 kΩ to 100 kΩ) pulldown resistor
CK	F1	5	I	Complementary clock input with a (10 kΩ to 100 kΩ) pulldown resistor
FBIN	E6	27	I	Feedback clock input
FBIN	F6	26	I	Complementary feedback clock input
FBOUT	H6	24	O	Feedback clock output
FBOUT	G6	25	O	Complementary feedback clock output
OE	F5	22	I	Output enable (asynchronous)
OS	D5	21	I	Output select (tied to GND or V _{DD})
GND	B2, B3, B4, B5, C2, C5, H2, H5, J2, J3, J4, J5	10		Ground
V _{DDQ}	D2, D3, D4, E2, E5, F2, G2, G3, G4, G5	1, 6, 9, 15, 20, 23, 28, 31, 36		Logic and output power
Y[0:9]	A2, A1, D1, J1, K3, A5, A6, D6, J6, K4	3, 11, 14, 16, 19, 29, 33, 34, 38, 39	O	Clock outputs
Y[0:9]	A3, B1, C1, K1, K2, A4, B6, C6, K6, K5	2, 12, 13, 18, 17, 30, 32, 35, 37, 40	O	Complementary clock outputs

FUNCTION TABLE

INPUTS					OUTPUTS					
AVDD	OE	OS	CK	CK	Y	Y	FBOUT	FBOUT	PLL	
GND	H	X	L	H	L	H	L	H	Bypassed/Off	
GND	H	X	H	L	H	L	H	L	Bypassed/Off	
GND	L	H	L	H	L _Z	L _Z	L	H	Bypassed/Off	
GND	L	L	H	L	L _Z Y7 Active	L _Z Y7 Active	H	L	Bypassed/Off	
1.8 V Nominal	L	H	L	H					On	
1.8 V Nominal	L	L	H	L	L _Z Y7 Active	L _Z Y7 Active	H	L	On	
1.8 V Nominal	H	X	L	H					On	
1.8 V Nominal	H	X	H	L	H	L	H	L	On	
1.8 V Nominal	X	X	L	L	L _Z	L _Z	L _Z	L _Z	Off	
X	X	X	H	H	Reserved					

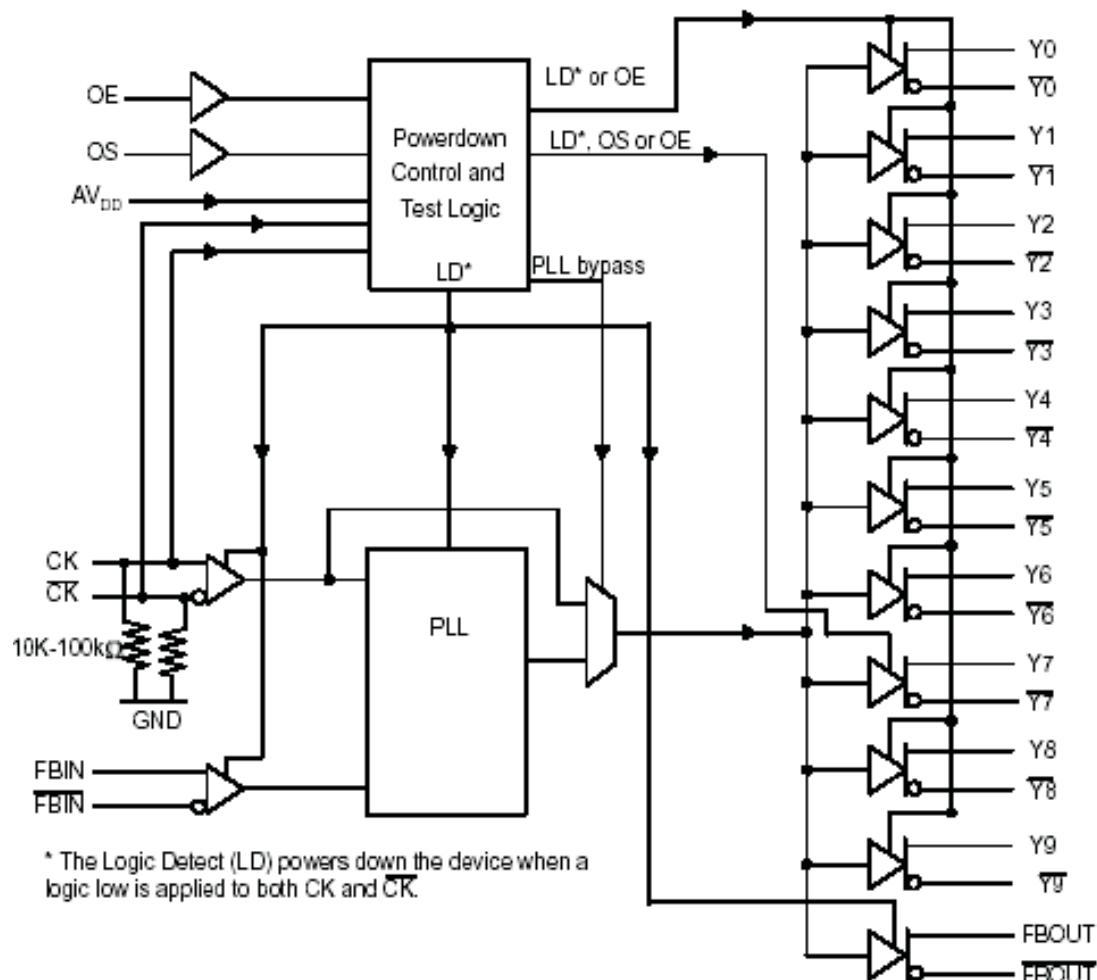


Figure 1. LOGIC DIAGRAM (POSITIVE LOGIC)

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range	V _{DDQ} or AV _{DD}	-0.5	2.5	V
V _I	Input voltage range ⁽²⁾⁽³⁾		-0.5	V _{DDQ} + 0.5	V
V _O	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{DDQ} + 0.5	V
I _{IK}	Input clamp current	V _I < 0 or V _I > V _{DDQ}		±50	mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{DDQ}		±50	mA
I _O	Continuous output current	V _O = 0 to V _{DDQ}		±50	mA
	Continuous current through each V _{DDQ} or GND			±100	mA
T _{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) This value is limited to 2.5 V maximum.

Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Output supply voltage, V _{DDQ}		1.7	1.8	1.9	V
	Supply Voltage, AV _{DD} ⁽¹⁾			V _{DDQ}		V
V _{IL}	Low-level input voltage ⁽²⁾	OE, OS			0.35 x V _{DDQ}	V
V _{IH}	High-level input voltage ⁽²⁾	CK, \overline{CK}		0.65 x V _{DDQ}		V
I _{OH}	High-level output current (see Figure 2)				-9	mA
I _{OL}	Low-level output current (see Figure 2)				9	mA
V _{IX}	Input differential-pair cross voltage		(V _{DDQ} /2) - 0.15		(V _{DDQ} /2) + 0.15	V
V _I	Input voltage level		-0.3		V _{DDQ} + 0.3	V
V _{ID}	Input differential voltage ⁽²⁾ (see Figure 9)	DC	0.3		V _{DDQ} + 0.4	V
		AC	0.6		V _{DDQ} + 0.4	V
T _A	Operating free-air temperature		-40		85	°C

- (1) The PLL is turned off and bypassed for test purposes when AV_{DD} is grounded. During this test mode, V_{DDQ} remains within the recommended operating conditions and no timing parameters are specified.
- (2) V_{ID} is the magnitude of the difference between the input level on CK and the input level on \overline{CK} , see [Figure 9](#) for definition. The CK and \overline{CK} , V_{IH} and V_{IL} limits define the dc low and high levels for the logic detect state.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	AV _{DD} , V _{DDQ}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}	Input	I _I = 18 mA	1.7			-1.2	V
V _{OH}	High-level output voltage	I _{OH} = -100 μ A	1.7 to 1.9	V _{DDQ} – 0.2			V
		I _{OH} = -9 mA	1.7	1.1			
V _{OL}	Low-level output voltage	I _{OL} = 100 μ A			0.1		V
		I _{OL} = 9 mA	1.7		0.6		
I _{O(DL)}	Low-level output current, disabled	V _{O(DL)} = 100 mV, OE = L	1.7	100			μ A
V _{OD}	Differential output voltage ⁽¹⁾		1.7	0.5			V
I _I	Input current	CK, \overline{CK}		1.9		\pm 250	μ A
		OE, OS, FBIN, \overline{FBIN}		1.9		\pm 10	
I _{DD(LD)}	Supply current, static (I _{DDQ} + I _{ADD})	CK and \overline{CK} = L	1.9		500		μ A
I _{DD}	Supply current, dynamic (I _{DDQ} + I _{ADD}) (see Note ⁽²⁾ for CPD calculation)	CK and \overline{CK} = 270 MHz. All outputs are open (not connected to a PCB)	1.9		135		mA
		All outputs are loaded with 2 pF and 120- Ω termination resistor	1.9		235		
C _I	Input capacitance	CK, \overline{CK}	V _I = V _{DD} or GND	1.8	2	3	pF
		FBIN, \overline{FBIN}		1.8	2	3	
C _{I(Δ)}	Change in input current	CK, \overline{CK}	V _I = V _{DD} or GND	1.8		0.25	
		FBIN, \overline{FBIN}		1.8		0.25	

(1) V_{OD} is the magnitude of the difference between the true and complimentary outputs. See Figure 9 for a definition.

(2) Total I_{DD} = I_{DDQ} + I_{ADD} = f_{CK} × C_{PD} × V_{DDQ}, solving for C_{PD} = (I_{DDQ} + I_{ADD})/(f_{CK} × V_{DDQ}) where f_{CK} is the input frequency, V_{DDQ} is the power supply, and C_{PD} is the power dissipation capacitance.

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
f _{CK}	Clock frequency (operating) ⁽¹⁾⁽²⁾	AV _{DD} , V _{DD} = 1.8 V \pm 0.1 V	10	400	MHz
	Clock frequency (application) ⁽¹⁾⁽³⁾		160	340	MHz
t _{DC}	Duty cycle, input clock		40%	60%	
t _L	Stabilization time ⁽⁴⁾			12	μ s

(1) The PLL must be able to handle spread spectrum induced skew.

(2) Operating clock frequency indicates a range over which the PLL must be able to lock, but in which it is not required to meet the other timing parameters (used for low speed system debug).

(3) Application clock frequency indicates a range over which the PLL must meet all timing parameters.

(4) Stabilization time is the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal after power up. During normal operation, the stabilization time is also the time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal when CK and \overline{CK} go to a logic low state, enter the power-down mode and later return to active operation. CK and \overline{CK} may be left floating after they have been driven low for one complete clock cycle.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see ⁽¹⁾) $V_{DD} = 1.8 \text{ V} \pm 0.1 \text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t_{en}	Enable time, OE to any Y/\bar{Y}	See Figure 11			8	ns	
t_{dis}	Disable time, OE to any Y/\bar{Y}	See Figure 11			8	ns	
$t_{jit(cc+)}$	Cycle-to-cycle period jitter ⁽²⁾	160 MHz to 190 MHz, see Figure 4	0	40		ps	
$t_{jit(cc-)}$			0	-40			
$t_{jit(cc+)}$	Cycle-to-cycle period jitter ⁽²⁾	160 MHz to 340 MHz, see Figure 4	0	30		ps	
$t_{jit(cc-)}$			0	-30			
$t_{(\omega)}$	Static phase offset time ⁽³⁾	See Figure 5	-50	50	ps		
$t_{(\omega)dyn}$	Dynamic phase offset time	See Figure 10	-15	15	ps		
$t_{sk(o)}$	Output clock skew	See Figure 6			35	ps	
$t_{jit(per)}$	Period jitter ⁽⁴⁾⁽²⁾	160 MHz to 190 MHz, see Figure 7	-30	30		ps	
		190 MHz to 340 MHz, see Figure 7	-20	20			
$t_{jit(hper)}$	Half-period jitter ⁽⁴⁾⁽²⁾	160 MHz to 190 MHz, see Figure 8	-115	115		ps	
		190 MHz to 250 MHz, see Figure 8	-70	70			
		250 MHz to 300 MHz, see Figure 8	-40	40			
		300 MHz to 340 MHz, see Figure 8	-60	60			
SR	Slew rate, OE	See Figure 3 and Figure 9	0.5			V/ns	
	Input clock slew rate	See Figure 3 and Figure 9	1	2.5	4		
	Output clock slew rate ⁽⁵⁾⁽⁶⁾ (no load)	See Figure 3 and Figure 9	1.5	2.5	3		
V_{ox}	Output differential-pair cross voltage ⁽⁷⁾	CDCU877, See Figure 2	$(V_{DDQ}/2) - 0.1$	$(V_{DDQ}/2) + 0.1$		V	
		CDCU877A ⁽⁸⁾ , See Figure 2 (0 - 85°C)	$(V_{DDQ}/2) - 0.1$	$(V_{DDQ}/2) + 0.1$			
SSC modulation frequency			30	33	kHz		
SSC clock input frequency deviation			0%	-0.5%			
PLL loop bandwidth			2		MHz		

- (1) There are two different terminations that are used with the following tests. The load/board in [Figure 2](#) is used to measure the input and output differential-pair cross voltage only. The load/board in [Figure 3](#) is used to measure all other tests. For consistency, equal length cables must be used.
- (2) This parameter is specified by design and characterization.
- (3) Phase static offset time does not include jitter.
- (4) Period jitter, half-period jitter specifications are separate specifications that must be met independently of each other.
- (5) The output slew rate is determined from the IBIS model with a 120- Ω load only.
- (6) To eliminate the impact of input slew rates on static phase offset, the input skew rates of reference clock input CK and \bar{CK} and feedback clock inputs FBIN and \bar{FBIN} are recommended to be nearly equal. The 2.5-V/ns skew rates are shown as a recommended target. Compliance with these typical values is not mandatory if it can adequately shown that alternative characteristics meet the requirements of the registered DDR2 DIMM application.
- (7) Output differential-pair cross voltage specified at the DRAM clock input or the test load.
- (8) V_{ox} of CDCU877A is on average 30 mV lower than that of CDCU877 for the same application.

PARAMETER MEASUREMENT INFORMATION

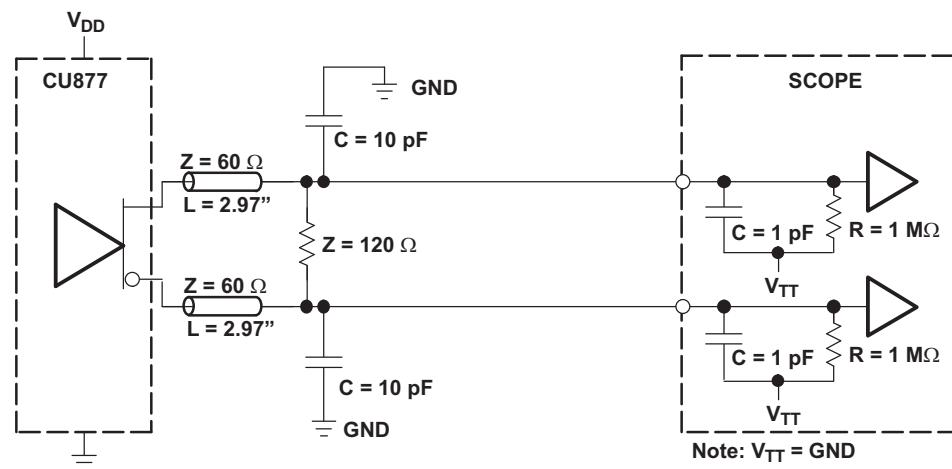


Figure 2. Output Load Test Circuit 1

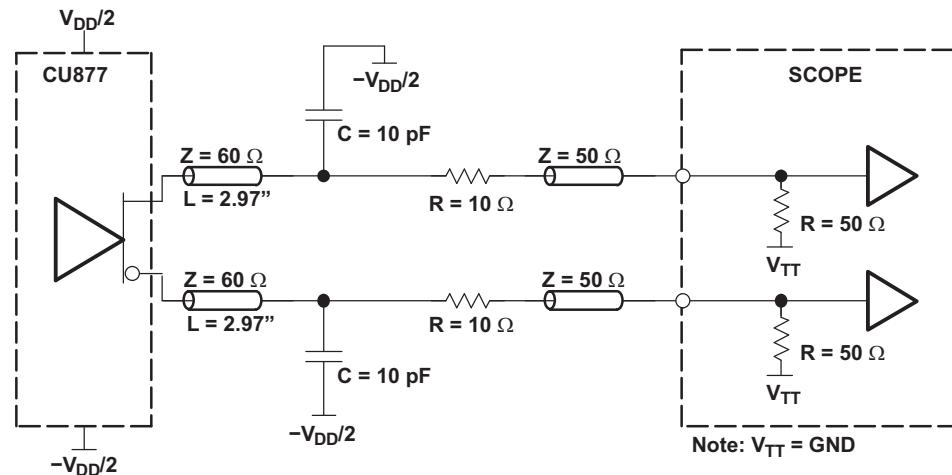


Figure 3. Output Load Test Circuit 2

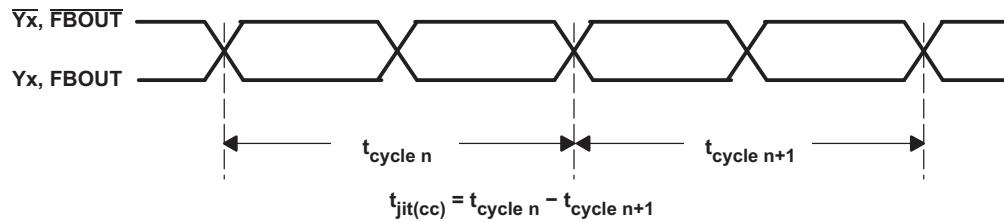


Figure 4. Cycle-To-Cycle Period Jitter

PARAMETER MEASUREMENT INFORMATION (continued)

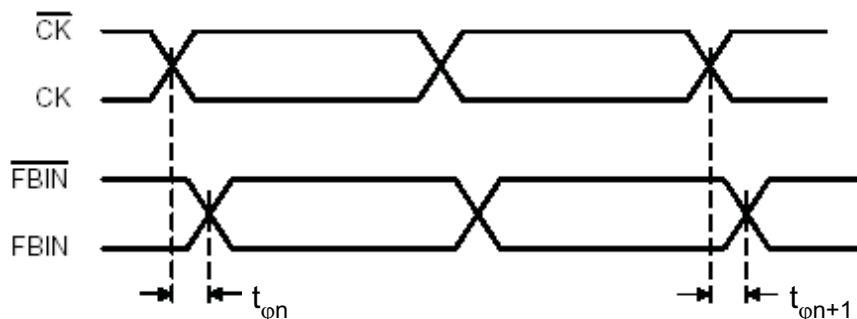


Figure 5. Static Phase Offset

$$t_\phi = \frac{\sum_{1}^{n=N} t_{\phi n}}{N}$$

(N is the large number of samples)

(N > 1000 samples)

(1)

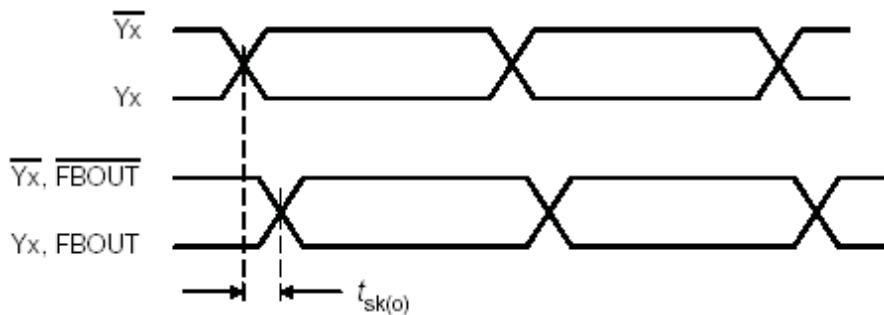


Figure 6. Output Skew

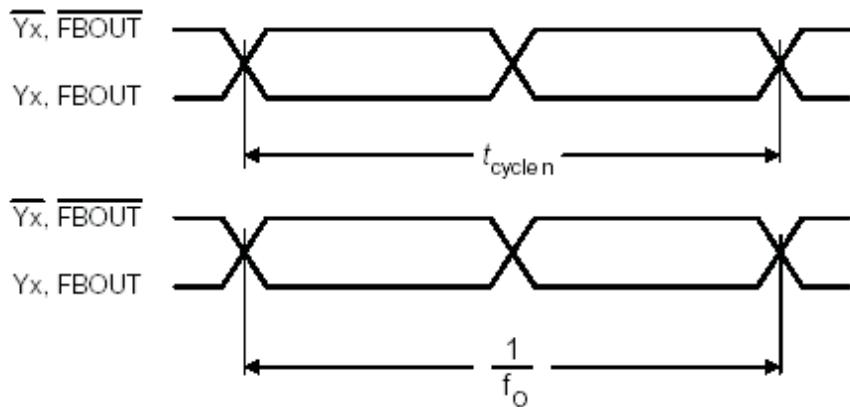


Figure 7. Period Jitter

$$t_{\text{jit(per)}} = t_{\text{cycle n}} - \frac{1}{f_o}$$

(f_o average input frequency measured at CK/CK̄)

(2)

PARAMETER MEASUREMENT INFORMATION (continued)

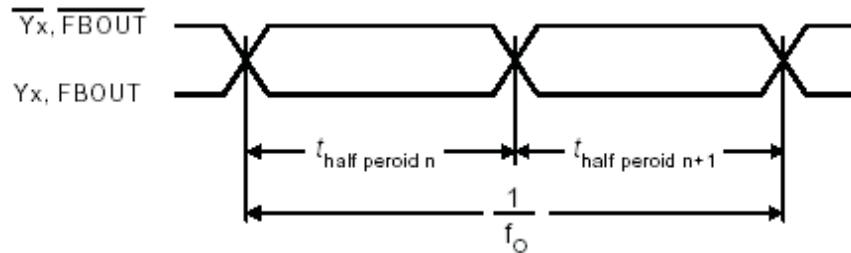


Figure 8. Half-Period Jitter

$$t_{\text{jit(hper)}} = t_{\text{half period n}} - \frac{1}{2 \times f_O}$$

n = any half cycle

(f_o average input frequency measured at CK/CK)

(3)

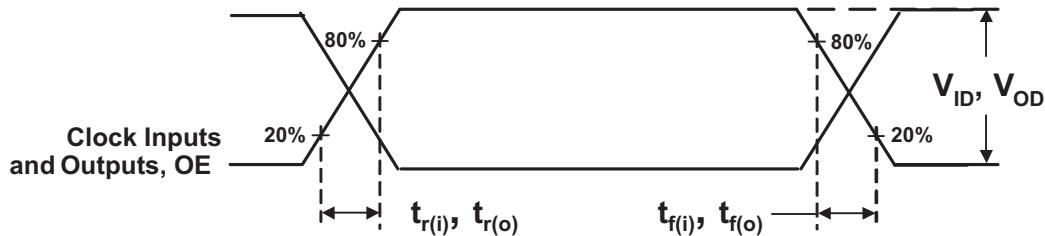


Figure 9. Input and Output Slew Rates

$$sIRR(i/o) = \frac{V_{80\%} - V_{20\%}}{t_r(i/o)} \quad sIRf(i/o) = \frac{V_{80\%} - V_{20\%}}{t_f(i/o)} \quad (4)$$

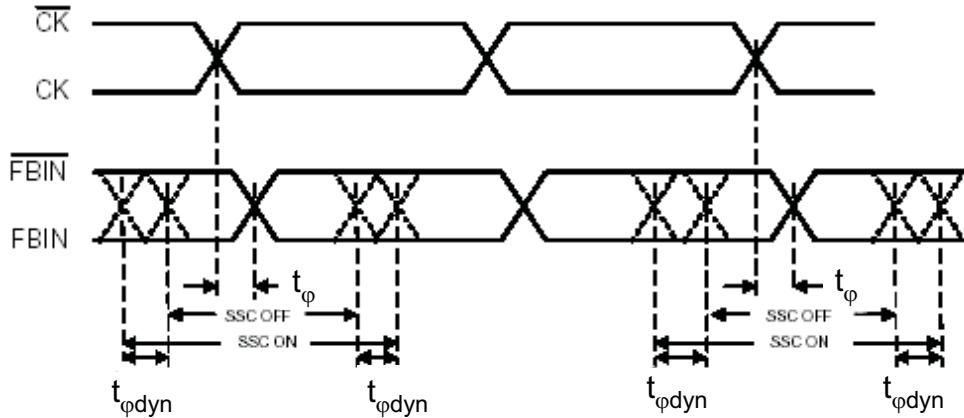


Figure 10. Dynamic Phase Offset

PARAMETER MEASUREMENT INFORMATION (continued)

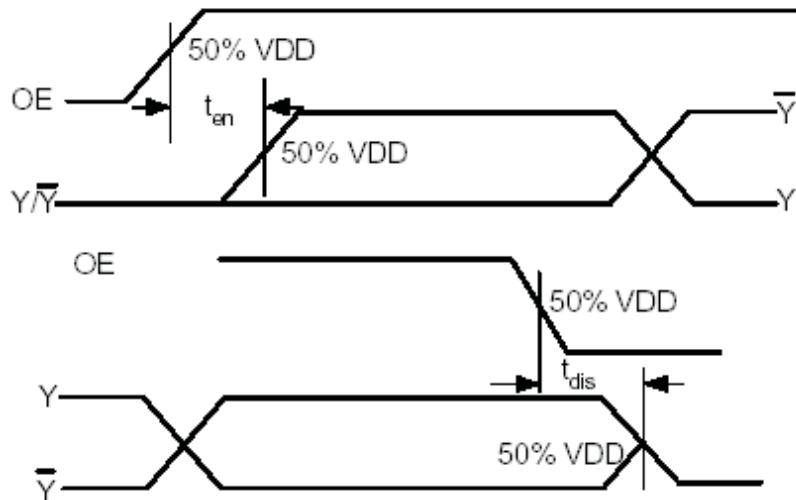
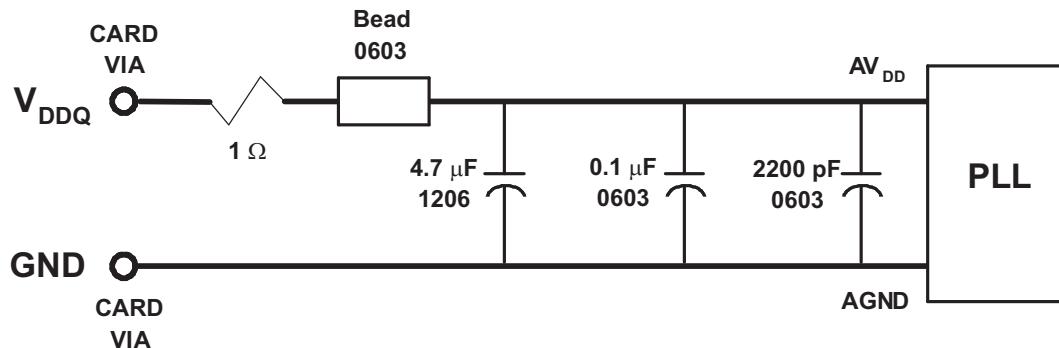


Figure 11. Time Delay Between OE and Clock Output (Y, Ȳ)

RECOMMENDED AV_{DD} FILTERING



- Place the 2200-pF capacitor close to the PLL.
- Use a wide trace for the PLL analog power and ground. Connect PLL and capacitors to AGND trace and connect trace to one GND via (farthest from the PLL).
- Recommended bead: Fair-Rite PN 2506036017Y0 or equivalent (0.8 Ω dc maximum, 600 Ω at 100 MHz).

Figure 12. Recommended AV_{DD} Filtering

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CDCU877ANMKR	ACTIVE	NFBGA	NMK	52	1000	RoHS & Green	SNAGCU	Level-3-260C-168 HR	-40 to 85	CDCU877A	Samples
CDCU877ANMKT	ACTIVE	NFBGA	NMK	52	250	RoHS & Green	SNAGCU	Level-3-260C-168 HR	-40 to 85	CDCU877A	Samples
CDCU877ARHAR	ACTIVE	VQFN	RHA	40	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877A	Samples
CDCU877ARHARG4	ACTIVE	VQFN	RHA	40	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877A	Samples
CDCU877ARHAT	ACTIVE	VQFN	RHA	40	250	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877A	Samples
CDCU877RHAR	ACTIVE	VQFN	RHA	40	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877	Samples
CDCU877RHAT	ACTIVE	VQFN	RHA	40	250	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877	Samples
CDCU877RHATG4	ACTIVE	VQFN	RHA	40	250	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877	Samples
CDCU877RTBR	ACTIVE	VQFN	RHA	40	2500	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 85	CDCU877	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

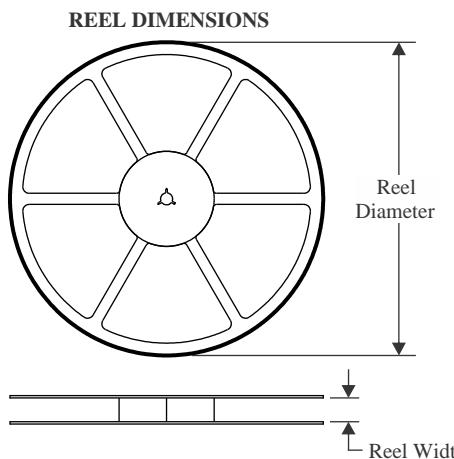
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

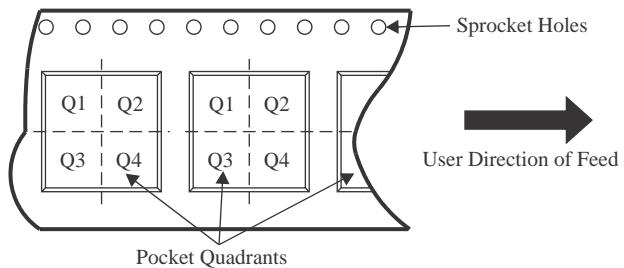
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCU877ANMKR	NFBGA	NMK	52	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
CDCU877ARHAR	VQFN	RHA	40	2500	330.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2
CDCU877ARHAT	VQFN	RHA	40	250	180.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2
CDCU877RHAR	VQFN	RHA	40	2500	330.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2
CDCU877RHAT	VQFN	RHA	40	250	180.0	16.4	6.3	6.3	1.1	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCU877ANMKR	NFBGA	NMK	52	1000	336.6	336.6	28.6
CDCU877ARHAR	VQFN	RHA	40	2500	356.0	356.0	35.0
CDCU877ARHAT	VQFN	RHA	40	250	210.0	185.0	35.0
CDCU877RHAR	VQFN	RHA	40	2500	356.0	356.0	35.0
CDCU877RHAT	VQFN	RHA	40	250	210.0	185.0	35.0

GENERIC PACKAGE VIEW

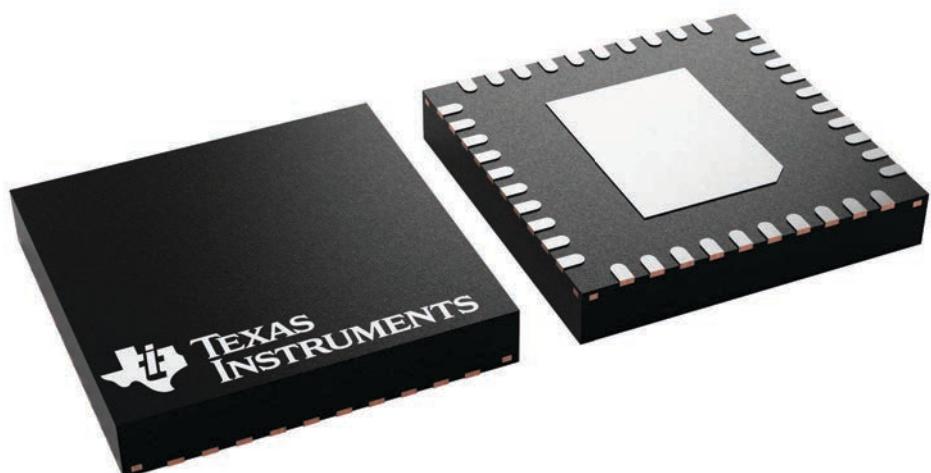
RHA 40

VQFN - 1 mm max height

6 x 6, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

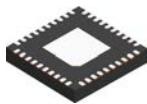
This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4225870/A

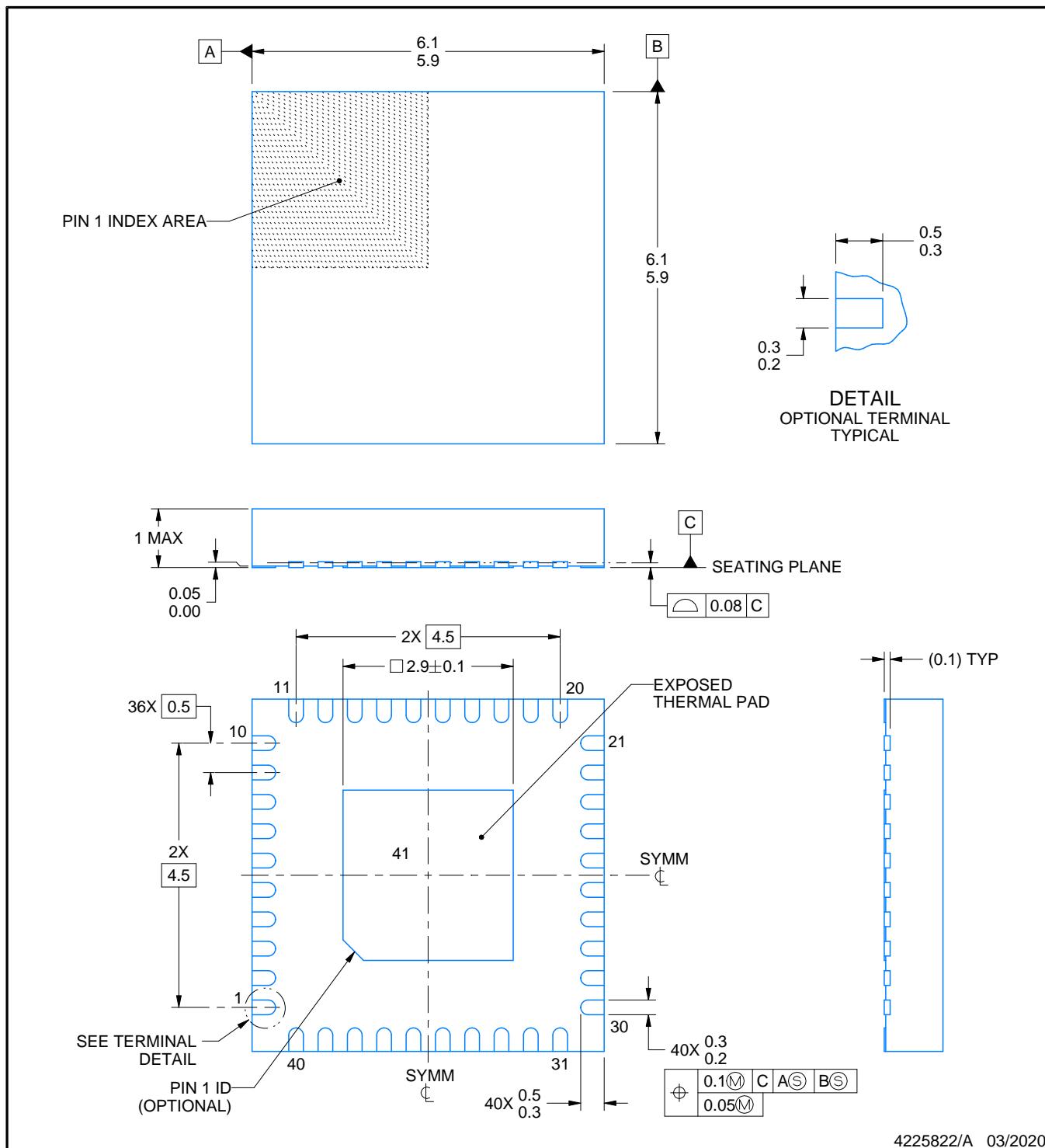
PACKAGE OUTLINE

RHA0040D



VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

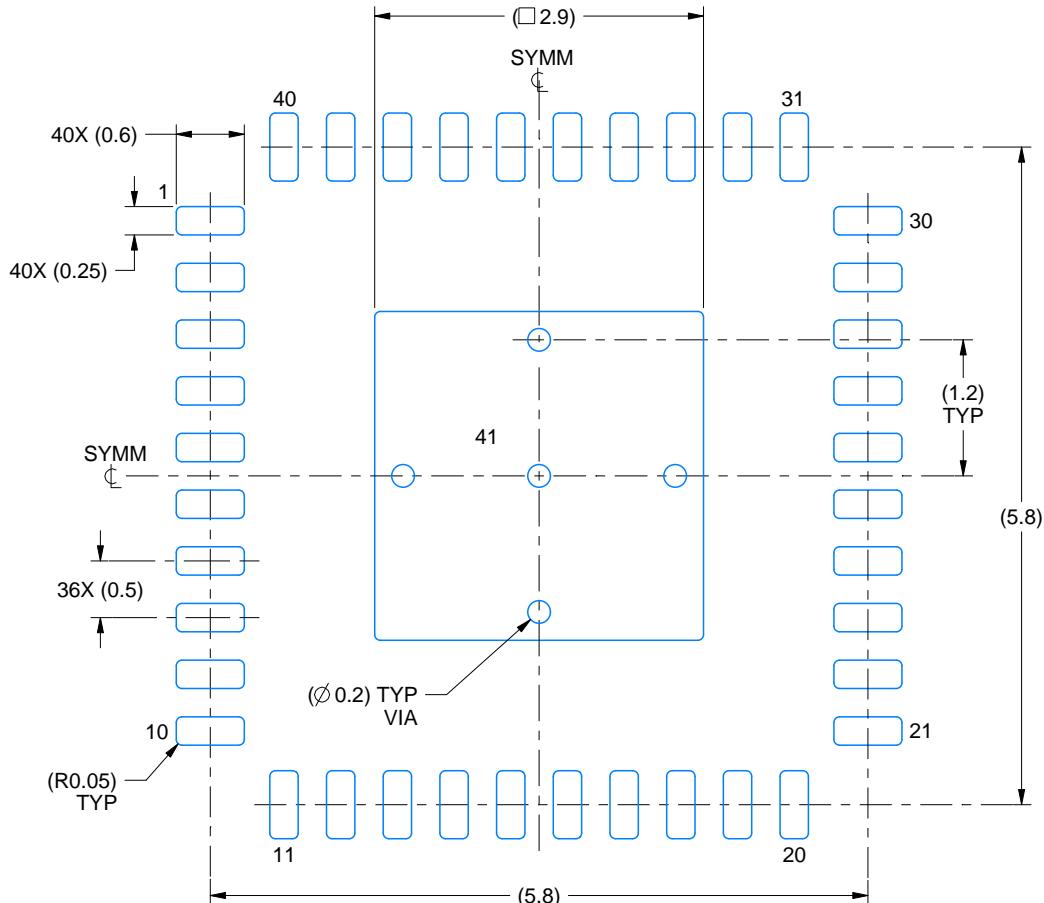
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

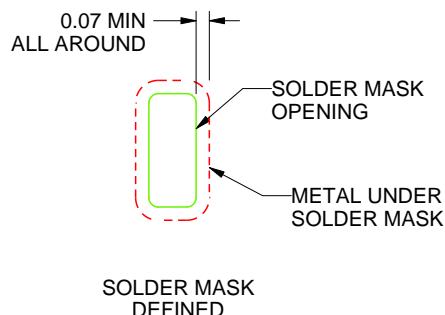
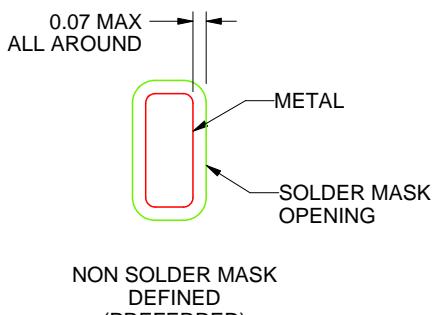
RHA0040D

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE



SOLDER MASK DETAILS

4225822/A 03/2020

NOTES: (continued)

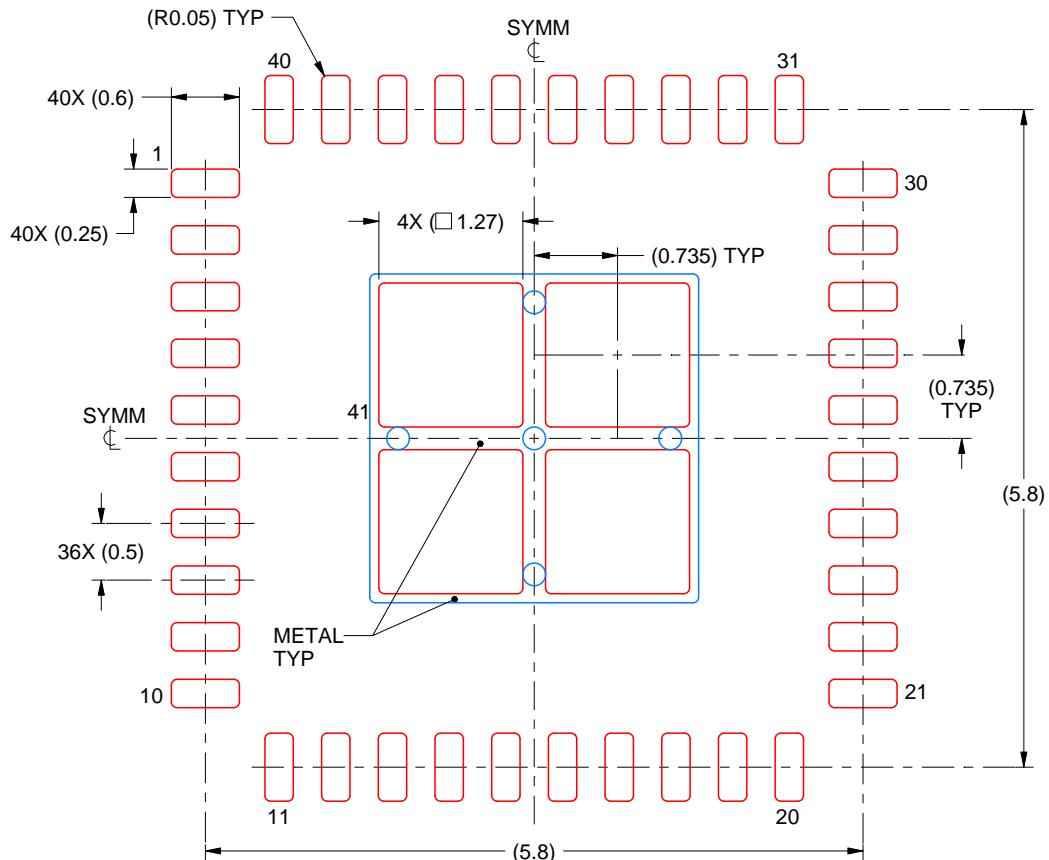
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view.

EXAMPLE STENCIL DESIGN

RHA0040D

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 41:
76.46% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:15X

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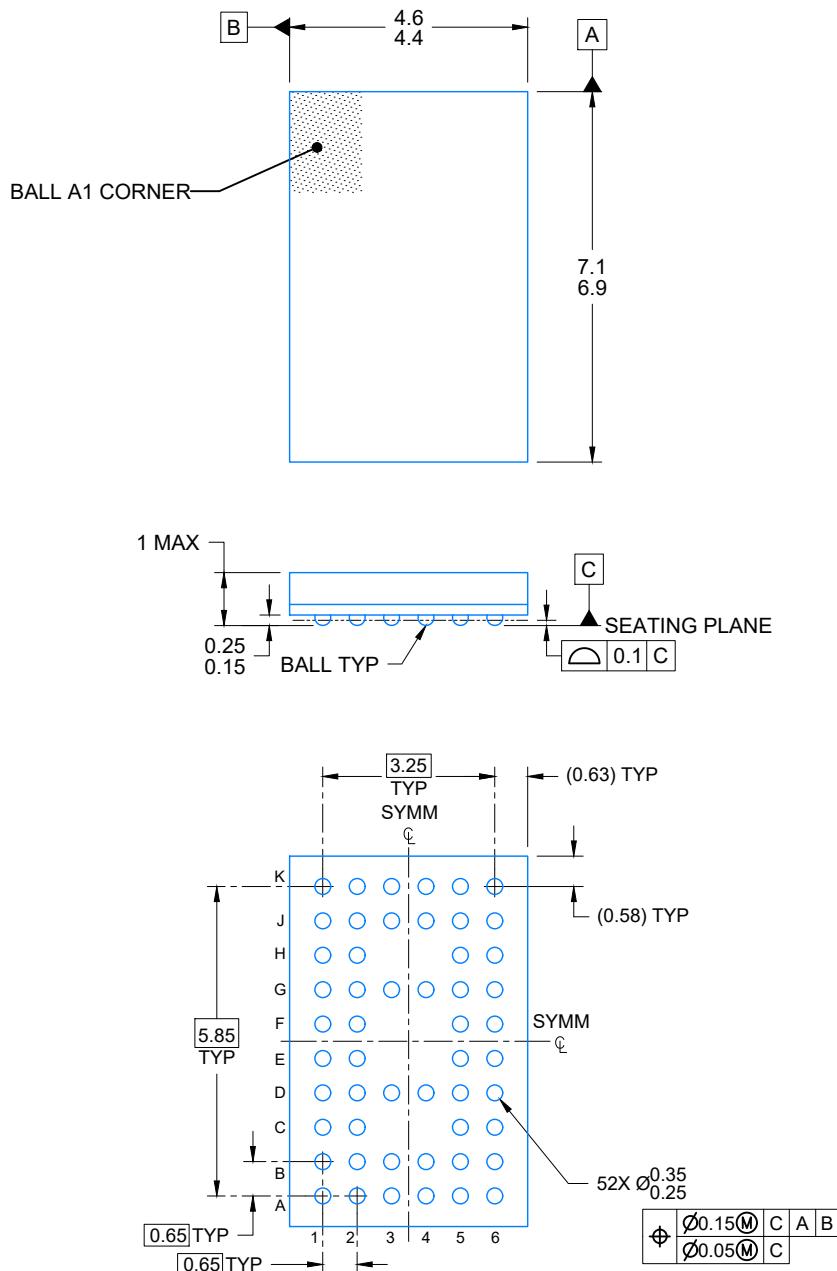
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

NMK0052A

PACKAGE OUTLINE NFBGA - 1 mm max height

PLASTIC BALL GRID ARRAY



4225135/A 08/2019

NOTES:

NanoFree is a trademark of Texas Instruments.

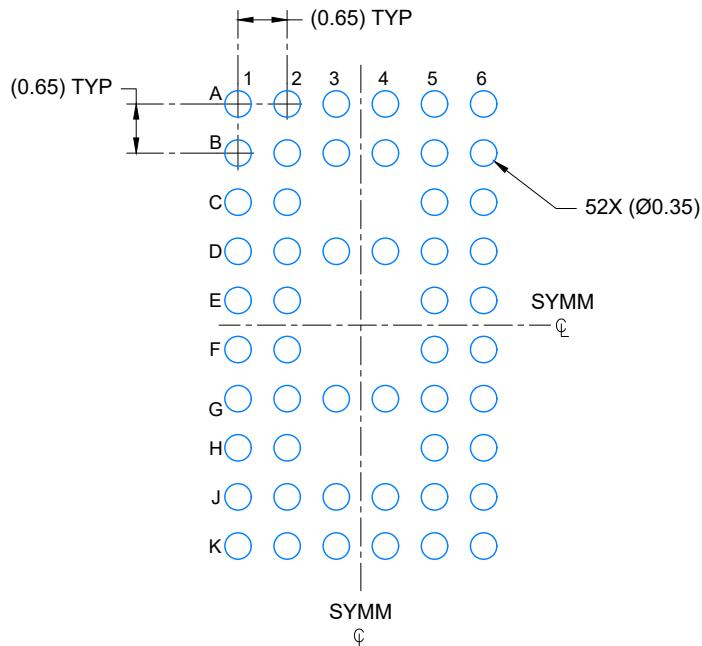
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

NFBGA - 1 mm max height

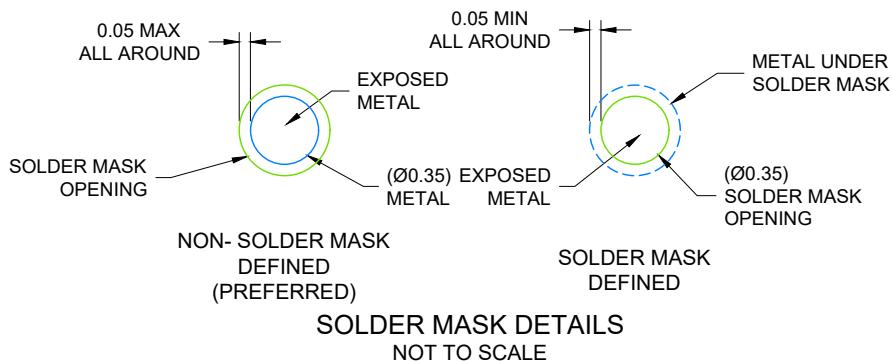
PLASTIC BALL GRID ARRAY

NMK0052A



LAND PATTERN EXAMPLE

SCALE: 10X



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NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).

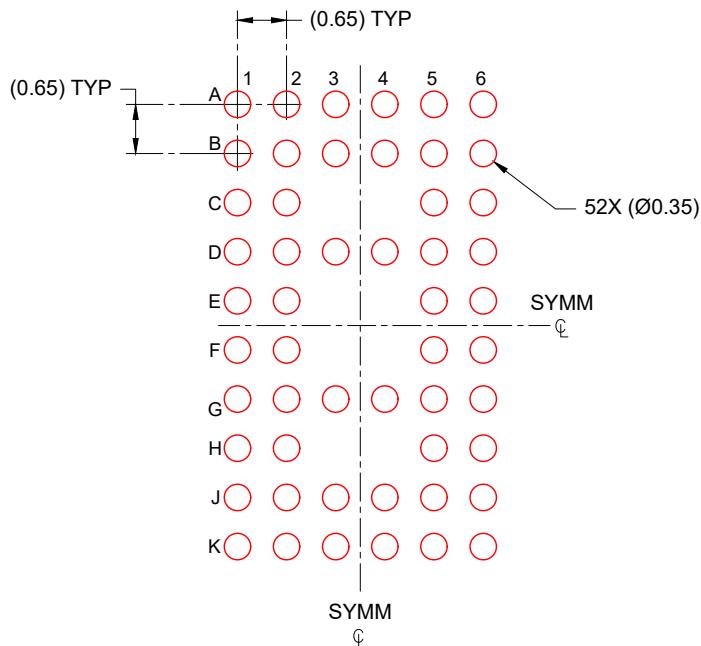


EXAMPLE STENCIL DESIGN

NFBGA - 1 mm max height

NMK0052A

PLASTIC BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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